

3/11/04

Substitute for form 1449A/PTO				Complete if Known	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (use as many sheets as necessary)				Application Number	10/799204
				Filing Date	03/11/2004
				First Named Inventor	Joan K. Vrtis
				Art Unit	3729
				Examiner Name	Tai van Nguyen
Sheet	1	of	3	Attorney Docket Number	42P13111D

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No.†	Document Number Number - Kind Code* (if known)	Publication Date Issue Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TN		US-2002/0009826 A1	01-24-2002	Chien	
		US-2002/0171132 A1	11-21-2002	Buchwalter et al.	
		US-4,858,073	08-15-1989	Gregory	
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		US-6,008,988	12-28-1999	Palmer	
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FOREIGN PATENT DOCUMENTS					
Examiner Initials*	Cite No.†	Foreign Patent Document Country Code* - Number* - Kind Code* (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear

Examiner Signature	<i>Tai van Nguyen</i>	Date Considered	10/31/05
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				Examiner Name	Tai van Nguyen
Sheet	2	of	3	Attorney Docket Number	42P13111D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.†	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T‡
TN		BATH, J., Selectron Corp., Lead Free Process Group Update, National Electronics Manufacturing Initiative, Jan. 17, 2001.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Enthone-OMI Inc., Conference Proceedings; Surface Mount International Conference, September 10, 1996, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424. 1 page.	
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TN		PARQUET, D., ET AL., OSP: The High Performance Surface Finish, Electronic Interconnect Conference, 1997.	

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TN		ROMM, D., ET AL., Evaluation of Ni/Pd-Finished ICs with Lead Free Solder Alloys, Texas Instruments Application Report SZZA024, Jan. 2001.	
		SOLBERG, V., Impact of PCB Surface Finish on SMT Assembly Process Yield, Application Note from Tesser Corp.	
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		WENGENROTH, KARL, ET AL., OSPS: Addressing Future Surface Finishing Needs, Enthone-OMI, Conference Proceedings, Surface Finishes Forum Conference, May 4, 2000, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.	
		Double Sided 4Mb SRAM Coupled Cap PBGA Card Assembly Guide, IBM Application Note, Feb. 1998.	
TN		Kester Solder Paste for Surface Mount and General Electronics Assemblies, Online Catalog of Preferred Products, 2001.	

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